## 产品规格承认书

## **SPECIFICATIONS**

客户:						
CUSTOMER:						
产品名称: DESCRIPTI	ON:	В	ipolar an	tenna	a	
客户型号:	PART NO:					
产品型号:	NO:					
日期: DATE:						
确认签字,盖 PLEASE RE			•	PECI	FICATION	FOR APPROVA
WITH YOUR	APPROVED	SIGNATU	RES			
Approved	LiuFei	Audit	LiuFei		Making	LiuXiaoMei
Customer	Acknowle	dges Si	gnature			
	Date	<b>e</b>				
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DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE CHIP2450 1608 Specification		DOCUMENT NO.	1608	SPEC REV.
111EE: CHIF 2430-1000 3	TITLE: CHIP2450-1608 Specification		1008	P1

### **PBX1608MC01 Specification**

#### 1. Features:

- Stable and reliable in performances
- Low profile, compact size
- RoHS compliance
- SMT processes compatible

#### 2. APPLICATIONS:

- ISM 2 . 4 GHz applications
- ZigBee/BLE applications
- Bluetooth earphone systems
- Hand-held devices when WiFi/Bluetooth functions are needed, e.g., Smart phones
- IEEE802.11 b/g/n
- Wireless PCMCIA cards or USB dongles

### 3. Part Number Information

AN 1608 S 24 LS
A B C D E

A	Patch ceramic antenna	Antenna
В	Size	1.5X0.8mm
C	Type of antenna	S: Bipolar
D	Frequency	2.4 ~ 2.5GHz
E	Product type	LS

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## 4. Product dimensions:

## 1608 Bipolar antenna

Figure	Symbol	Dimension (mm)
L	L (Long)	1.5 ± 0.10
	₩ (Wide)	0.8 ± 0.10
w w	⊺ (Thickness)	0.50 ± 0.10
A	(Width of electrode)	0.2 ± 0.10

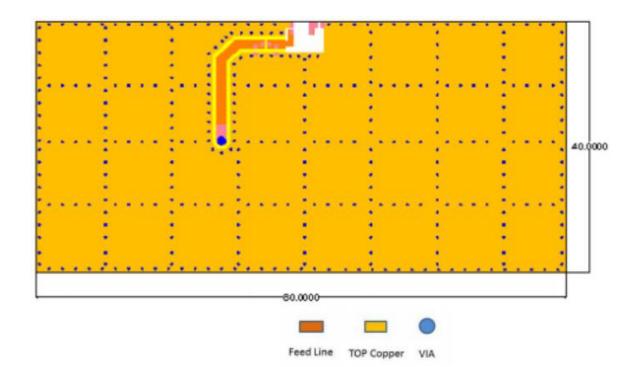
## 5. Electrical Specification:

Specification					
Part Number	AN1608S24LS				
Central Frequency	2450	MHz			
Bandwidth	120 (Min.)	MHz			
Return Loss	-6.5 (Max)	dB			
Peak Gain	2.73	dBi			
Impedance	50	Ohm			
Operating Temperature	-40 <sup>~</sup> +85	C			
Maximum Power	4	W			
Resistance to Soldering Heats	10 ( @ 260C)	sec.			
Polarization	Linear				
Azimuth Beamwidth	Omni-directional				
Termination	Ni / Sn (Leadless)				

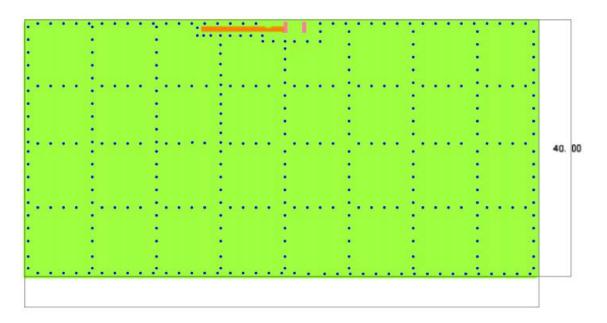
Remark: Bandwidth & Peak Gain was measured under evaluation board of next page

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## 6. 1608 Bipolar antennas are recommended PCB



## **2<sup>nd</sup> Evaluation Board Dimension**



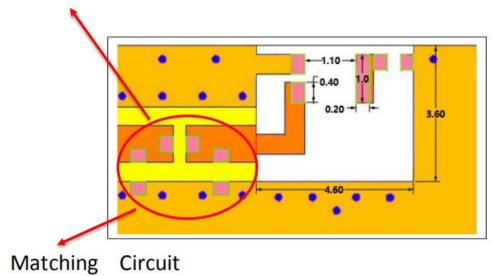
Matching elements are recommended using murata  $\pm$  1% inductance, capacitance.

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## Clearance area (Size=4.6\*3.6mm)

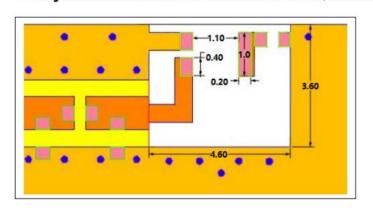


## 50 ohm transmission Line



# 

## 2 Layout Dimensions in Clearance area(Size=8.0\*3.0mm)

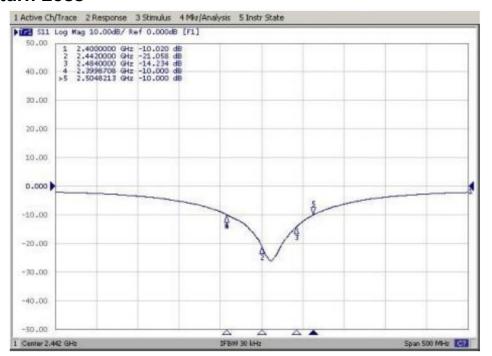




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### 7.1 Measurement Results

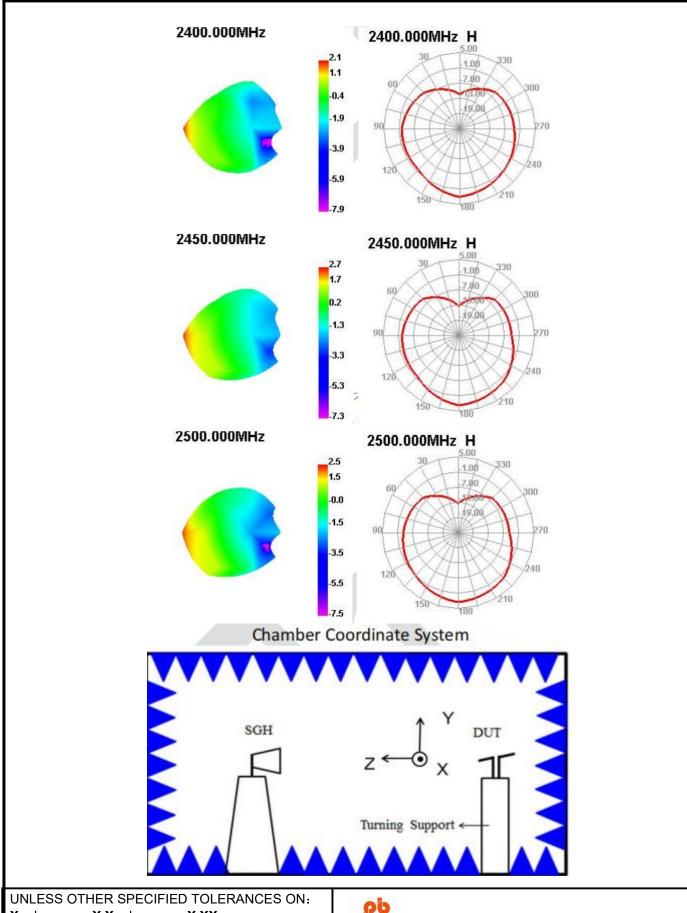
#### **Return Loss**



## 7.2 Radiation Pattern

	Efficiency	Peak Gain	Directivity
2400MHz	51.56 %	2.06 dBi	4.94dBi
2450MHz	51.99 %	2.73 dBi	5.57 dBi
2500MHz	48.23 %	2.48 dBi	5.65 dBi

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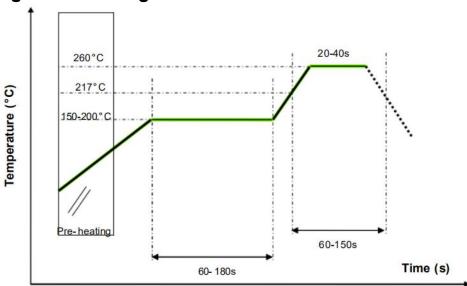


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## 8. Raliability and Test Condictions

Test item	Test condition / Test method	Specification		
Solderability JIS C 0050-4.6 JESD22-B102D	*Solder bath temperature : 235 ± 5°C  *Immersion time : 2 ± 0.5 sec  Solder : Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder.		
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.		
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5± 1 sec.  Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.		
Resistance to soldering heat  JIS C 0050-5.4	*Preheating temperature: 120~150C,  1 minute.  *Solder temperature: 270±5°C  *Immersion time: 10±1 sec  Solder: Sn3Ag0.5Cu for lead-free  Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage.  Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.  Loss of metallization on the edges of each electrode shall not exceed 25%.		

## 9. Soldering and Mounting



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## 10. Matters needing attention in antenna application

- 1. If space allows, it is best not to choose too small antenna size.
- 2. 2. It is best to have a large clearance area between the antenna and nearby objects: otherwise it will be difficult to match and adjust, and the radiation pattern will be severely distorted.
- 3. There should be no wiring or grounding beneath the antenna.
- 4. Antennas should not be placed too close to metal objects, such as batteries, chips, etc., should not overlap with the battery and other metal objects.
- 5. Pay attention to the internal cable (such as the battery power cord) better not too close to the antenna.
- 6. A bipolar antenna needs a reasonable ground to work best.
- 7.Antenna matching on the final product solution can reduce the adjustment cycle: in the light plate often requires repeated adjustment.
- 8. If not matched, the same antenna placed on a completely different layout board may not work properly.
- 9. Do not use a metal case or plastic case with metal around the antenna. Do not use very thin antenna feeders, feeders should have a certain width, should not be less than 0.1 mm.
- 10. Calculating the impedance of the feeder based on the thickness and dielectric constant of the PCB, 50 ohms will make the adjustment of the antenna easier, chip Antenna Assembly should be as far away from batteries, EMI protection materials, folding speakers, metal screws, LCD screen, etc.

## 11. Storage and Transportation Information

#### Storage Conditions

To maintain the solderability of terminal electrodes:

- 1. Temperature and humidity conditions: 10~ 400 and 30~70% RH.
- Recommended products should be used within 6 months from the time of delivery.
- The packaging material should be kept where no chlorine or sulfur exists in the air

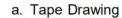
#### **Transportation Conditions**

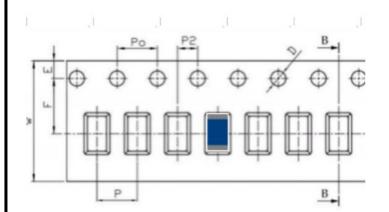
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- The use of tweezers or vacuum pick up is strongly recommended for individual components.
- Bulk handling should ensure that abrasion and mechanical shock are minimized.

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## 12. Packing

- (1) Quantity/Reel: 5000 pcs/Reel
- (2) Plastic tape:



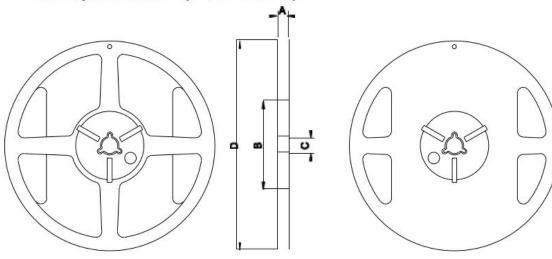


b. Tape Dimensions (unit: mm)

	5.0	83
Feature	Specifications	Tolerances
W	8 00	±0 30
Р	4.00	±0.10
E	1.75	±0.10
F	3 50	±0 10
P2	2.00	±0.10
D	1.50	+0. 10
	1.50	-0.00
Po	4.00	±0.10
10Po	40 00	±0 20

#### c. Reel Drawing





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7" x 8 mm